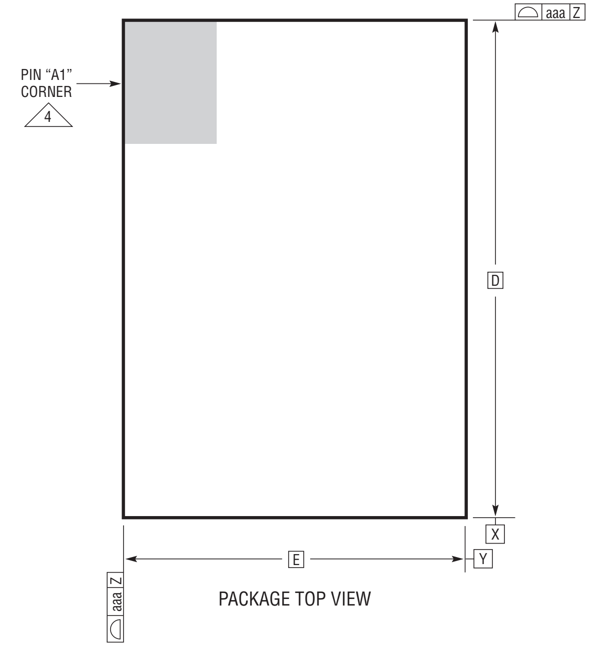
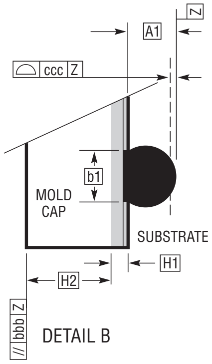
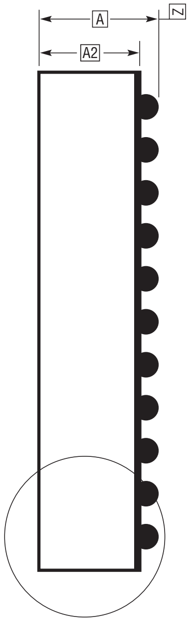
BGA Package
88-Lead (15mm × 11.25mm × 5.01mm)
(Reference LTC DWG # 05-08-1541 Rev A)



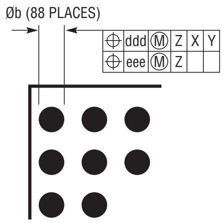
PACKAGE TOP VIEW



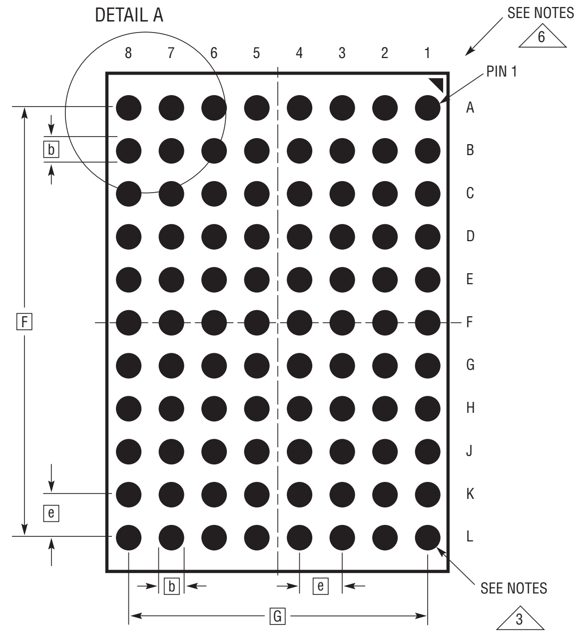
DETAIL B



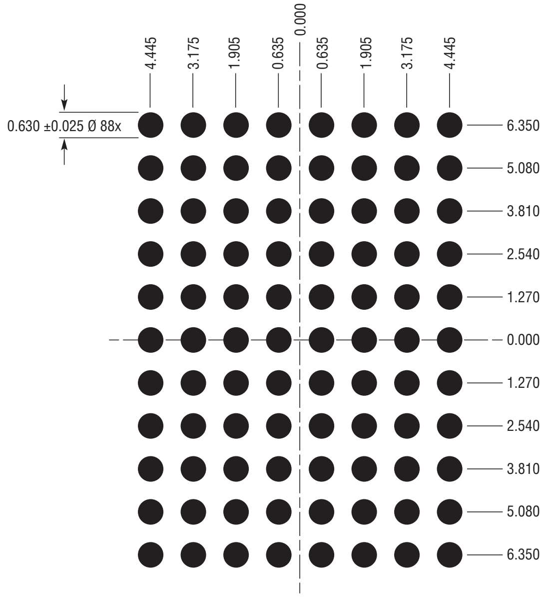
DETAIL B
PACKAGE SIDE VIEW



DETAIL A



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	4.81	5.01	5.21	
A1	0.50	0.60	0.70	BALL HT
A2	4.31	4.41	4.51	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D		15.00		
E		11.25		
e		1.27		
F		12.70		
G		8.89		
H1	0.36	0.41	0.46	SUBSTRATE THK
H2	3.95	4.00	4.05	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 88

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

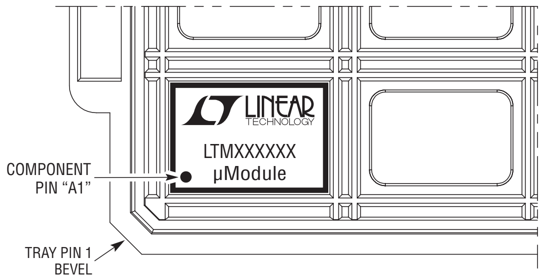
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 88 0517 REV A